

Application Data Sheet

APPLICATION INFORMATION

Application Number::

Filing Date::

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

Suggested Group Art Unit::

CD-ROM or CD-R?:: None

Number of CD Disks:

Number of Copies of CDs::

Sequence Submission?::

Computer Readable From (CRF)?:: No

Number of Copies of CRF::

Title:: METHOD OF WIRING SEMICONDUCTOR
INTEGRATED CIRCUIT, SEMICONDUCTOR
INTEGRATED CIRCUIT, AND COMPUTER
PRODUCT

Attorney Docket Number:: 401558

Request for Early Publication?:: No

Request for Non-Publication?:: No

Suggested Drawing Figure::

Total Drawing Sheets:: 11

Small Entity?:: No

Latin Name::

Variety denomination name::

Petition Included?:: No

Petition Type::

Licensed US Govt. Agency::

Contract or Grant Numbers::

Secrecy Order in Parent Appl.?:: No

CORRESPONDENCE INFORMATION

PCorrespondence Customer Number:: 23548

Phone:: (202) 737-6770

Fax:: (202) 737-6776

E-mail Address:: dcmal@leydig.com

REPRESENTATIVE INFORMATION

Representative Customer Number:: 23548

Representative Designation:: Registration Number:: Representative Name::

DOMESTIC PRIORITY INFORMATION

Application:: Continuity Type:: Parent Application:: Parent Filing Date::

FOREIGN APPLICATION INFORMATION

Country::	Application Number::	Filing Date::	Priority Claimed
Japan	2001-215793	07/16/01	Yes

ASSIGNEE INFORMATION

Assignee name::	Mitsubishi Denki Kabushiki Kaisha
Street of mailing address::	2-3, Marunouchi 2-chome, Chiyoda-ku
City of mailing address::	Tokyo
State or Province of mailing address::	
Country of mailing address::	Japan
Postal or Zip Code of mailing address::	100-8310